

Trench gate field-stop IGBT, HB series 650 V, 30 A high-speed in a TO-247 long leads package

Datasheet - production data

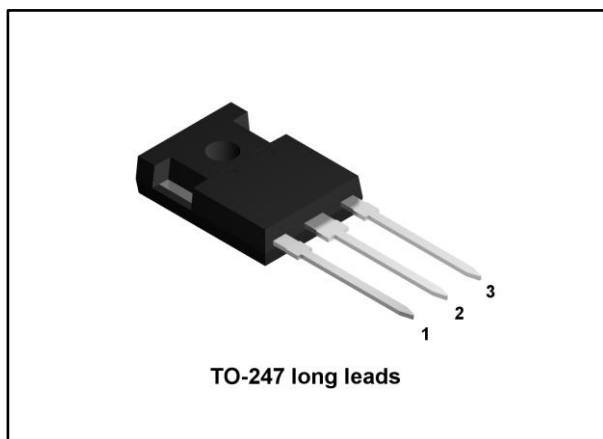
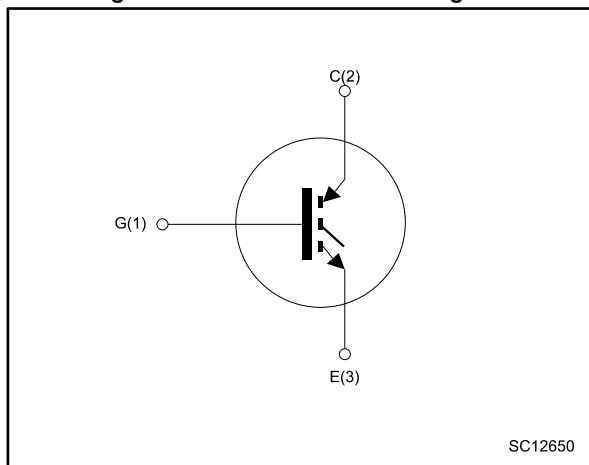


Figure 1: Internal schematic diagram



Features

- Maximum junction temperature: $T_J = 175\text{ }^{\circ}\text{C}$
- High-speed switching series
- Minimized tail current
- $V_{CE(sat)} = 1.55\text{ V(typ)} @ I_C = 30\text{ A}$
- Safe paralleling
- Tight parameter distribution
- Low thermal resistance

Applications

- Photovoltaic inverters
- High-frequency converters

Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the new HB series of IGBTs, which represents an optimum compromise between conduction and switching loss to maximize the efficiency of any frequency converter. Furthermore, the slightly positive $V_{CE(sat)}$ temperature coefficient and very tight parameter distribution result in safer paralleling operation.

Table 1: Device summary

Order code	Marking	Package	Packing
STGWA30H65FB	GWA30H65FB	TO-247 long leads	Tube

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage ($V_{GE} = 0$ V)	650	V
I_C	Continuous collector current at $T_C = 25$ °C	60	A
	Continuous collector current at $T_C = 100$ °C	30	
$I_{CP}^{(1)}$	Pulsed collector current	120	A
V_{GE}	Gate-emitter voltage	±20	V
P_{TOT}	Total dissipation at $T_C = 25$ °C	260	W
T_{STG}	Storage temperature range	-55 to 150	°C
T_J	Operating junction temperature range	-55 to 175	

Notes:

⁽¹⁾Pulse width limited by maximum junction temperature

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case	0.58	°C/W
R_{thJA}	Thermal resistance junction-ambient	50	

2 Electrical characteristics

$T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise specified

Table 4: Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0\text{ V}$, $I_C = 2\text{ mA}$	650			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}$, $I_C = 30\text{ A}$		1.55	2	V
		$V_{GE} = 15\text{ V}$, $I_C = 30\text{ A}$, $T_J = 125\text{ }^{\circ}\text{C}$		1.65		
		$V_{GE} = 15\text{ V}$, $I_C = 30\text{ A}$, $T_J = 175\text{ }^{\circ}\text{C}$		1.75		
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}$, $I_C = 1\text{ mA}$	5	6	7	V
I_{CES}	Collector cut-off current	$V_{GE} = 0\text{ V}$, $V_{CE} = 650\text{ V}$			25	μA
I_{GES}	Gate-emitter leakage current	$V_{CE} = 0\text{ V}$, $V_{GE} = \pm 20\text{ V}$			± 250	nA

Table 5: Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	$V_{CE} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{GE} = 0\text{ V}$	-	3659	-	pF
C_{oes}	Output capacitance		-	101	-	
C_{res}	Reverse transfer capacitance		-	76	-	
Q_g	Total gate charge	$V_{CC} = 520\text{ V}$, $I_C = 30\text{ A}$, $V_{GE} = 0\text{ to }15\text{ V}$ (see Figure 23: "Gate charge test circuit")	-	149	-	nC
Q_{ge}	Gate-emitter charge		-	25	-	
Q_{gc}	Gate-collector charge		-	62	-	

Table 6: Switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$, $I_C = 30\text{ A}$, $V_{GE} = 15\text{ V}$, $R_G = 10\ \Omega$ (see Figure 22: "Test circuit for inductive load switching")	-	37	-	ns
t_r	Current rise time		-	14.6	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1643	-	A/ μ s
$t_{d(off)}$	Turn-off-delay time		-	146	-	ns
t_f	Current fall time		-	23	-	ns
$E_{on(1)}$	Turn-on switching energy		-	151	-	mJ
$E_{off(2)}$	Turn-off switching energy		-	293	-	mJ
E_{ts}	Total switching energy		-	444	-	mJ
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$, $I_C = 30\text{ A}$, $V_{GE} = 15\text{ V}$, $R_G = 10\ \Omega$, $T_J = 175\text{ }^\circ\text{C}$ (see Figure 22: "Test circuit for inductive load switching")	-	35	-	ns
t_r	Current rise time		-	16.1	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1496	-	A/ μ s
$t_{d(off)}$	Turn-off-delay time		-	158	-	ns
t_f	Current fall time		-	65	-	ns
$E_{on(1)}$	Turn-on switching energy		-	175	-	mJ
$E_{off(2)}$	Turn-off switching energy		-	572	-	mJ
E_{ts}	Total switching energy		-	747	-	mJ

Notes:

⁽¹⁾Including the reverse recovery of the diode. Turn-on times and energy have been measured applying as freewheeling an external SiC diode STPSC206W.

⁽²⁾Including the tail of the collector current.

2.1 Electrical characteristics (curves)

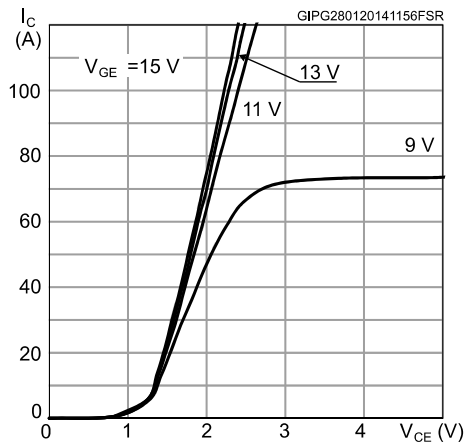
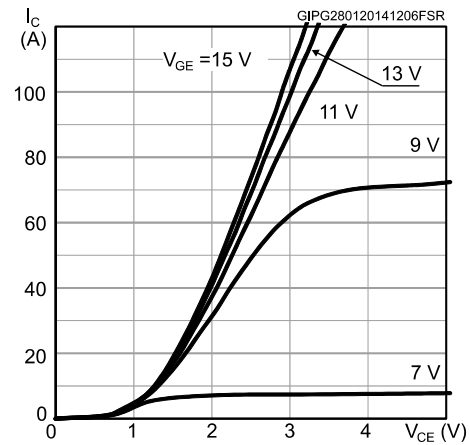
Figure 2: Output characteristics ($T_J = 25\text{ }^{\circ}\text{C}$)Figure 3: Output characteristics ($T_J = 175\text{ }^{\circ}\text{C}$)

Figure 4: Transfer characteristics

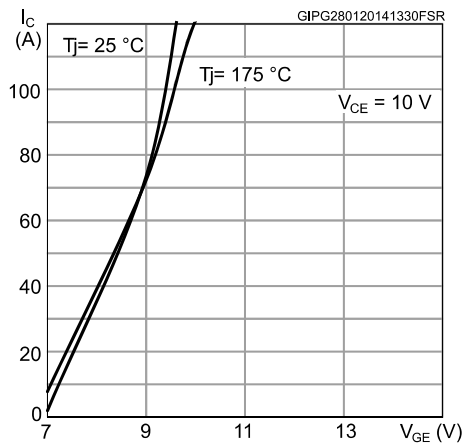


Figure 5: Collector current vs. case temperature

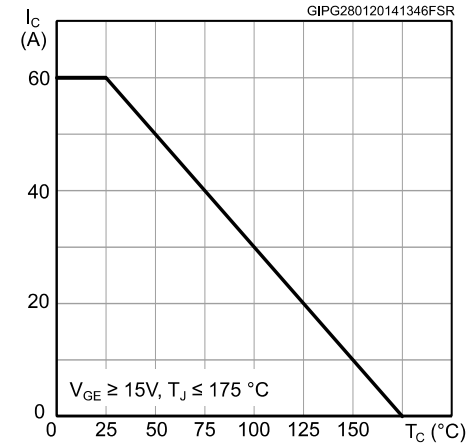
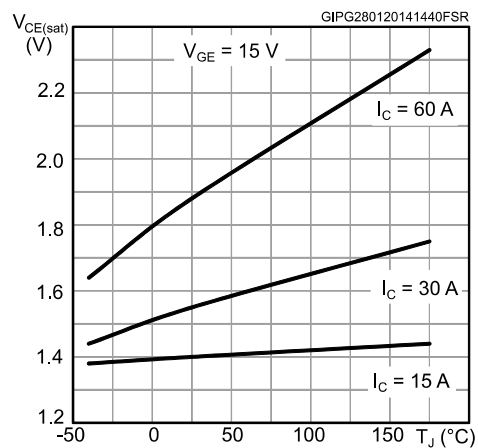
Figure 6: $V_{CE(sat)}$ vs. junction temperature

Figure 7: Power dissipation vs. case temperature

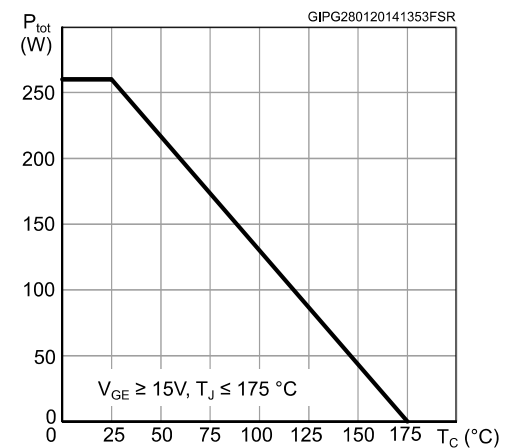


Figure 8: Forward bias safe operating area

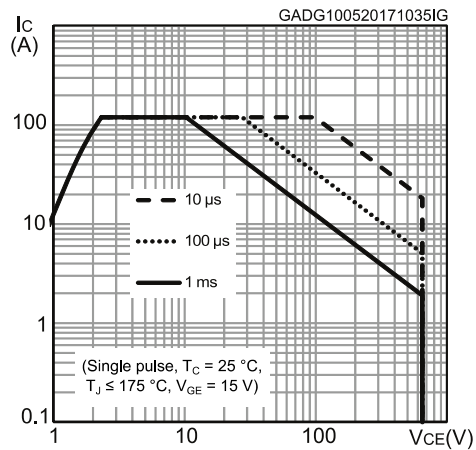


Figure 9: Collector current vs. switching frequency

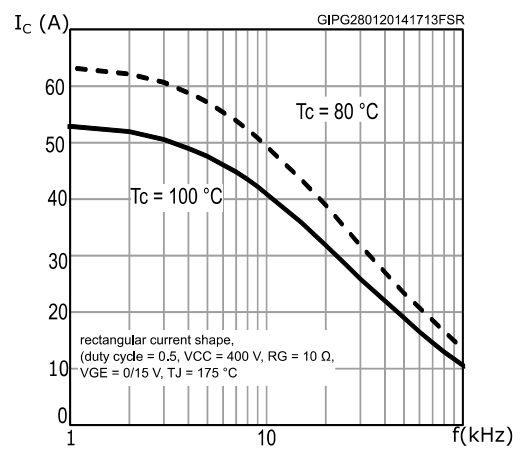
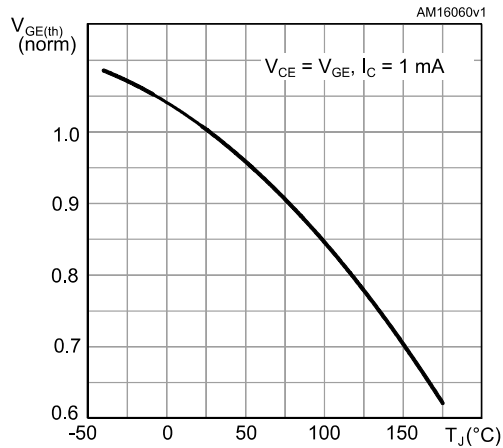
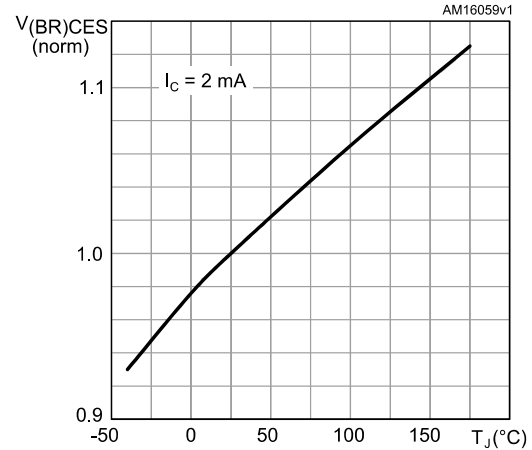
Figure 10: Normalized $V_{GE(th)}$ vs. junction temperatureFigure 11: Normalized $V_{(BR)CES}$ vs. junction temperature

Figure 12: Switching energy vs. temperature

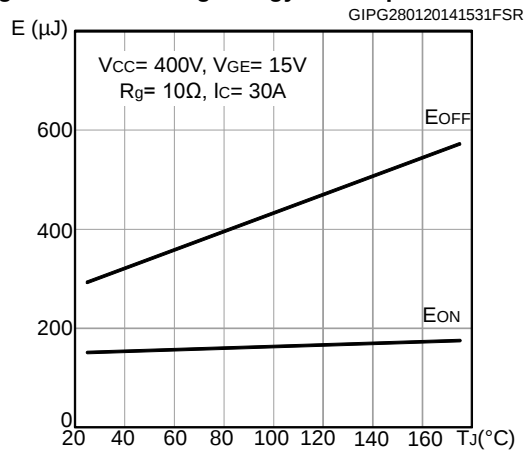


Figure 13: Switching energy vs. gate resistance

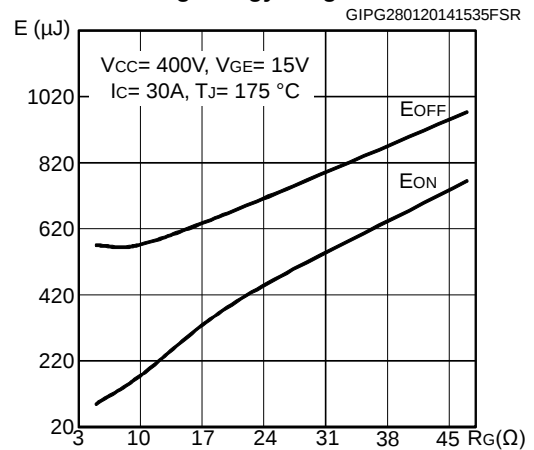


Figure 14: Switching energy vs. collector current

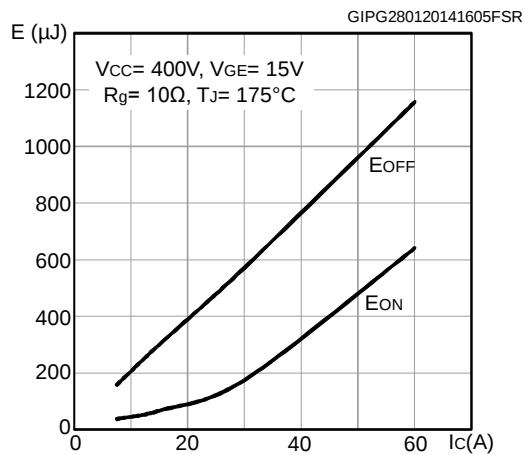


Figure 15: Switching energy vs. collector emitter voltage

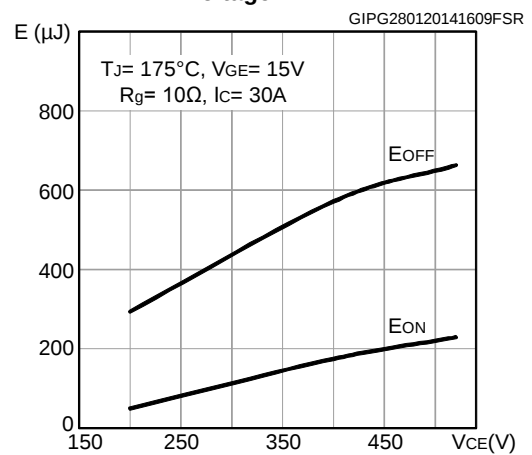


Figure 16: Switching times vs. collector current

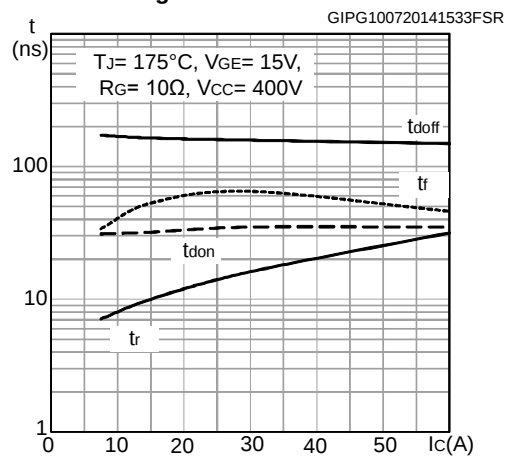


Figure 17: Switching times vs. gate resistance

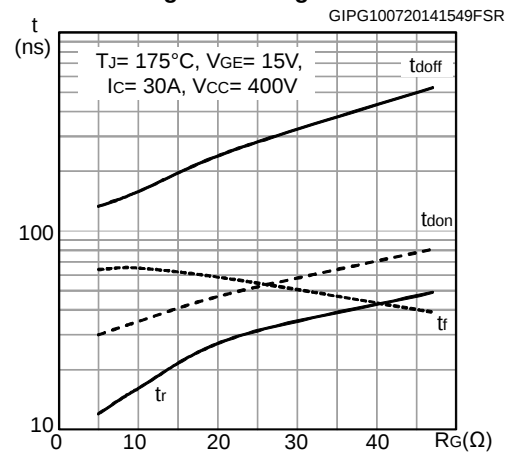


Figure 18: Capacitance variations

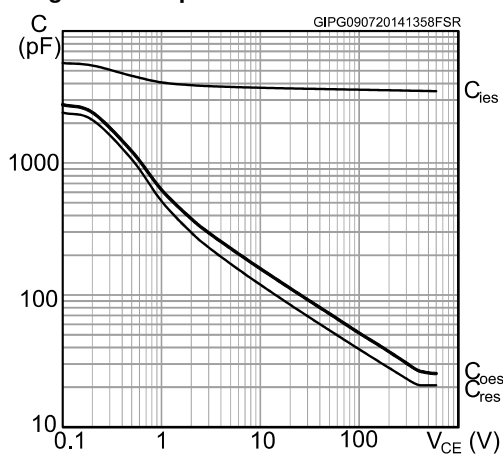
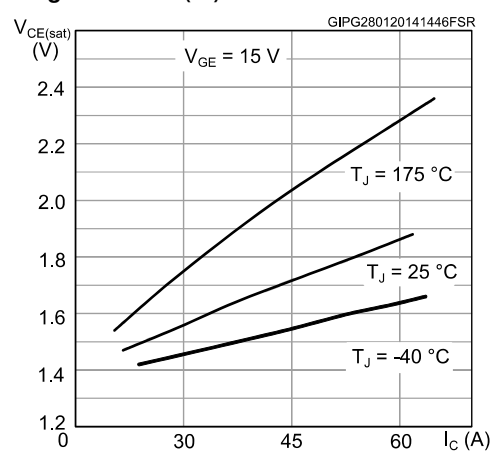
Figure 19: $V_{CE(sat)}$ vs. collector current

Figure 20: Gate charge vs. gate-emitter voltage

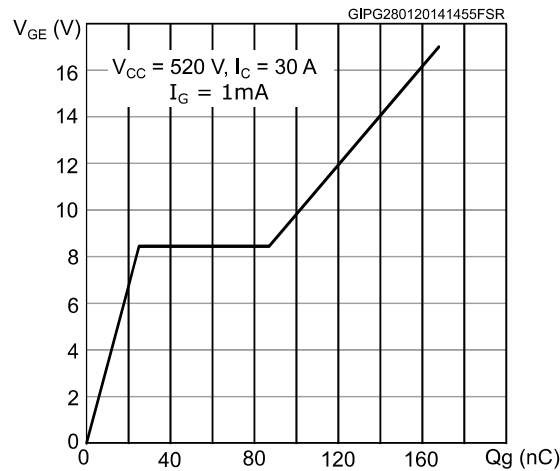
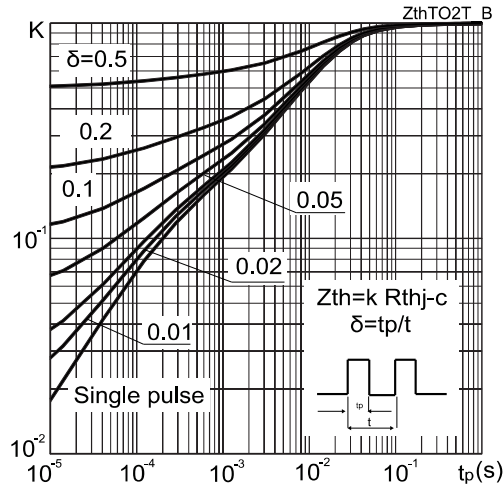
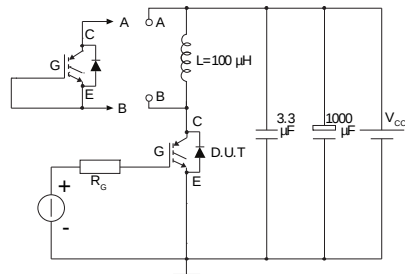


Figure 21: Thermal impedance



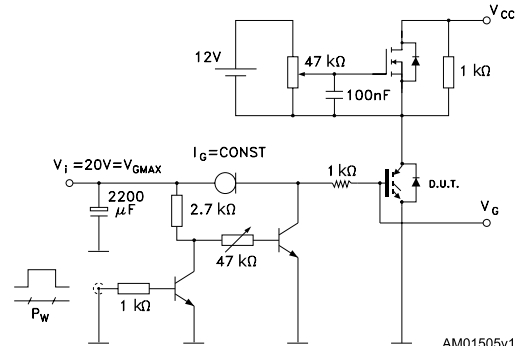
3 Test circuits

Figure 22: Test circuit for inductive load switching



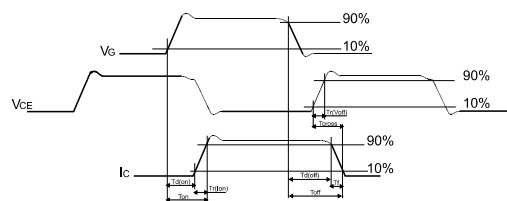
AM01504v1

Figure 23: Gate charge test circuit



AM01505v1

Figure 24: Switching waveform



AM01506v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 TO-247 long leads package information

Figure 25: TO-247 long leads package outline

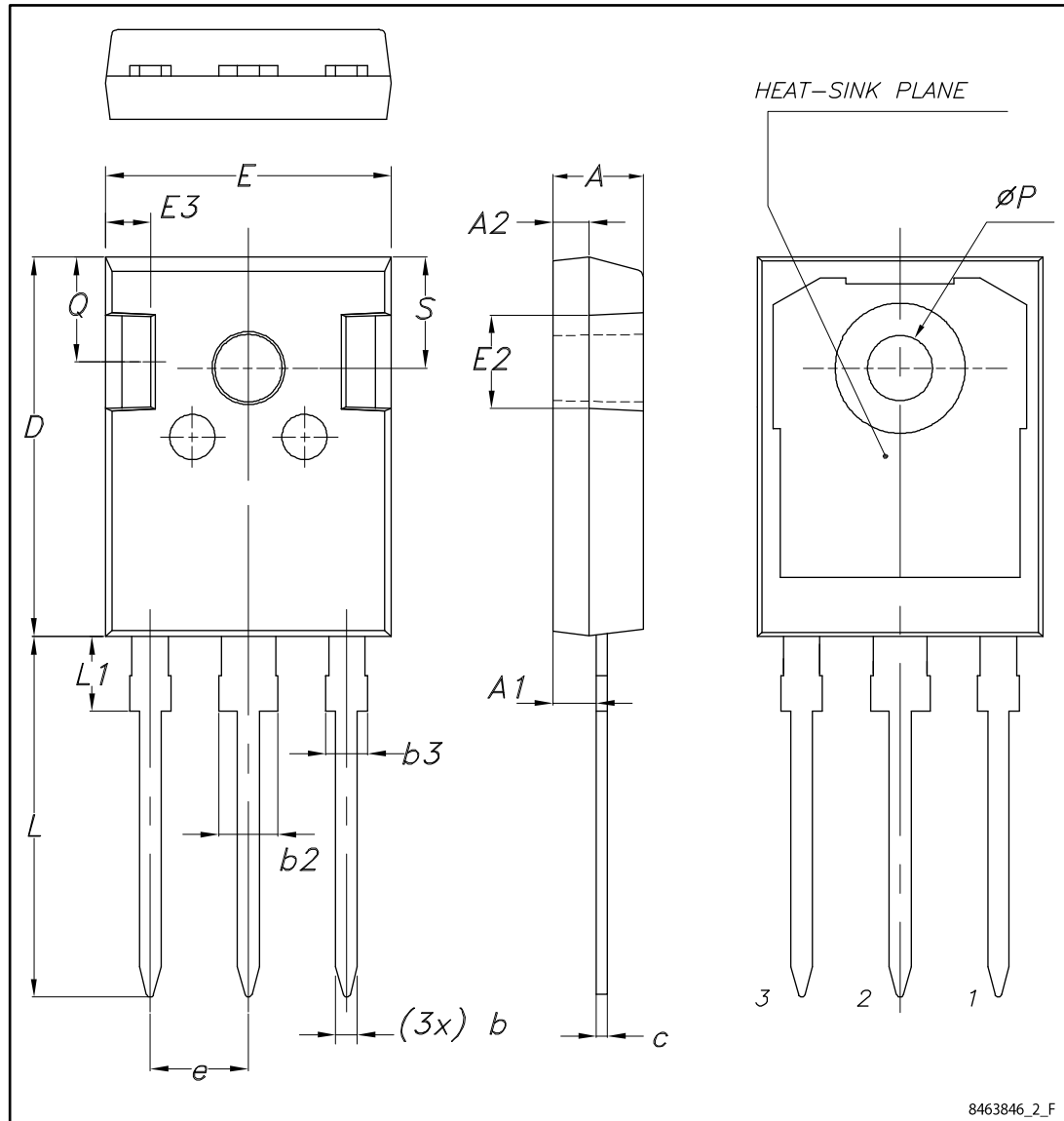


Table 7: TO-247 long leads package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.26
b2			3.25
b3			2.25
c	0.59		0.66
D	20.90	21.00	21.10
E	15.70	15.80	15.90
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1			4.30
P	3.50	3.60	3.70
Q	5.60		6.00
S	6.05	6.15	6.25

5 Revision history

Table 8: Document revision history

Date	Revision	Changes
10-May-2017	1	Initial release

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